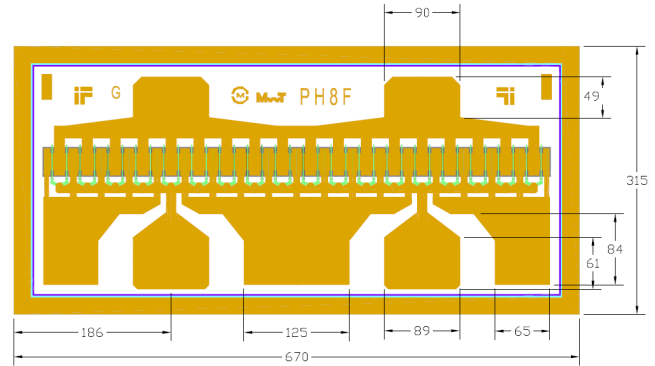


## Features:

- 30 dBm of Power at 12 GHz
- 11 dB Small Signal Gain at 12 GHz
- 42% PAE at 12 GHz
- 0.25 x 1200 Micron Refractory Metal/Gold Gate
- Excellent for Power, Gain, and High Power Added Efficiency
- Ideal for Commercial, Military, Hi-Rel Space Applications



Chip Dimensions: 670 x 315 microns  
Chip Thickness: 100 microns

## Description:

The MwT-PH8F is a AlGaAs/InGaAs pHEMT (Pseudomorphic-High-Electron-Mobility-Transistor) device whose nominal 0.25 micron gate length and 1200 micron gate width make it ideally suited for applications requiring high-gain and medium power up to 18 GHz frequency range. The device is equally effective for either wideband or narrow-band applications. The chip is produced using reliable metal systems and passivated to insure excellent reliability.

## Electrical Specifications: at $T_a = 25^\circ\text{C}$

| PARAMETERS & CONDITIONS  | SYMBOL | FREQ   | UNITS | MIN | TYP  |
|--|--------|--------|-------|-----|------|
| Output Power at 1dB Compression<br>$V_{ds}=8.0\text{V}$ $I_{ds}=0.7 \times I_{DSS}$    | P1dB   | 12 GHz | dBm   |     | 27.5 |
| Saturated Power<br>$V_{ds}=8.0\text{V}$ $I_{ds}=0.7 \times I_{DSS}$                    | Psat   | 12 GHz | dBm   |     | 30.0 |
| Output Third Order Intercept Point<br>$V_{ds}=8.0\text{V}$ $I_{ds}=0.7 \times I_{DSS}$ | OIP3   | 12 GHz | dBm   |     | 35.0 |
| Small Signal Gain<br>$V_{ds}=8.0\text{V}$ $I_{ds}=0.7 \times I_{DSS}$                  | SSG    | 12 GHz | dB    |     | 11.0 |
| Power Added Efficiency at P1dB<br>$V_{ds}=8.0\text{V}$ $I_{ds}=0.7 \times I_{DSS}$     | PAE    | 12 GHz | %     |     | 42   |

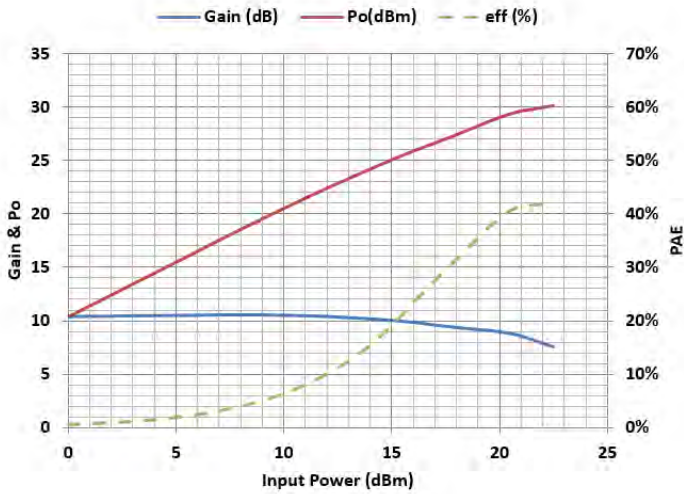
Note:  $I_{ds}$  should be between 40% and 80% of  $I_{DSS}$ . Currently, our data shows  $I_{ds}$  at 70% of  $I_{DSS}$ . Low  $I_{ds}$  will improve efficiency, but high  $I_{ds}$  will make Psat and IP3 better.

## DC Specifications: at $T_a = 25^\circ\text{C}$

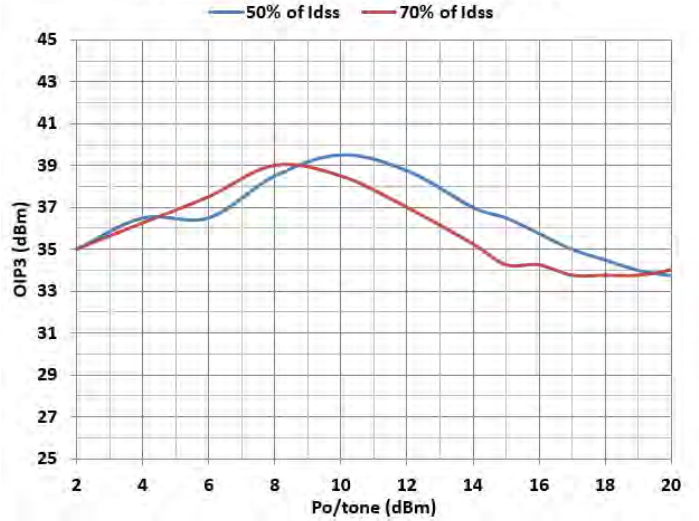
| PARAMETERS & CONDITIONS  | SYMBOL        | UNITS    | MIN | TYP   | MAX  |
|--|---------------|----------|-----|-------|------|
| Saturated Drain Current<br>$V_{ds}= 3.0\text{ V}$ $V_{gs}= 0.0\text{ V}$ | $I_{DSS}$     | mA       | 250 |       | 300  |
| Transconductance<br>$V_{ds}= 2.5\text{ V}$ $V_{gs}= 0.0\text{ V}$        | Gm            | mS       |     | 400   |      |
| Pinch-off Voltage<br>$V_{ds}= 3.0\text{ V}$ $I_{ds}= 1.0\text{ mA}$      | $V_p$         | V        |     | -0.8  | -1.0 |
| Gate-to-Source Breakdown Voltage<br>$I_{gs}= -0.3\text{ mA}$             | BVGSO         | V        |     | -17.0 |      |
| Gate-to-Drain Breakdown Voltage<br>$I_{gd}= -0.3\text{ mA}$              | BVGDO         | V        |     | -18.0 |      |
| Chip Thermal Resistance  | Chip & 71 pkg | $R_{th}$ | C/W | 40    |      |

\* Overall  $R_{th}$  depends on case mounting

MwT-PH8F, Gain, Po & PAE vs Pin at 12GHz  
Vds=8V; Idq=0.7xIDSS



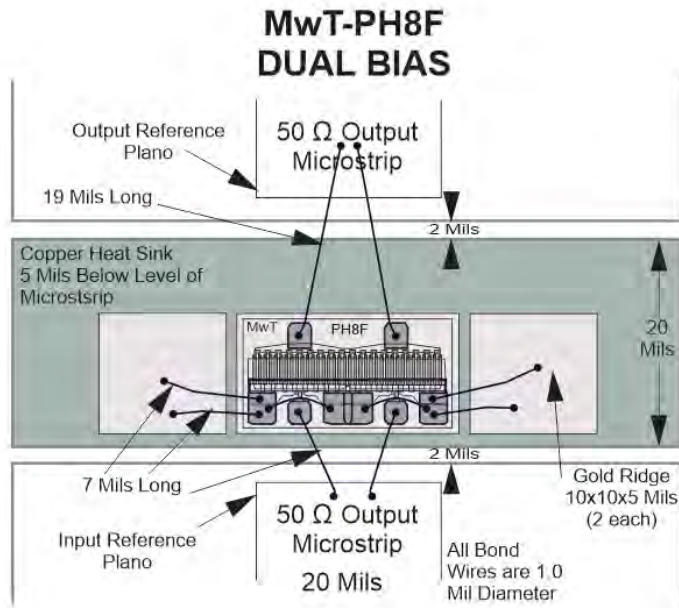
MwT-PH8F, OIP3 at different Idq vs Po/tone



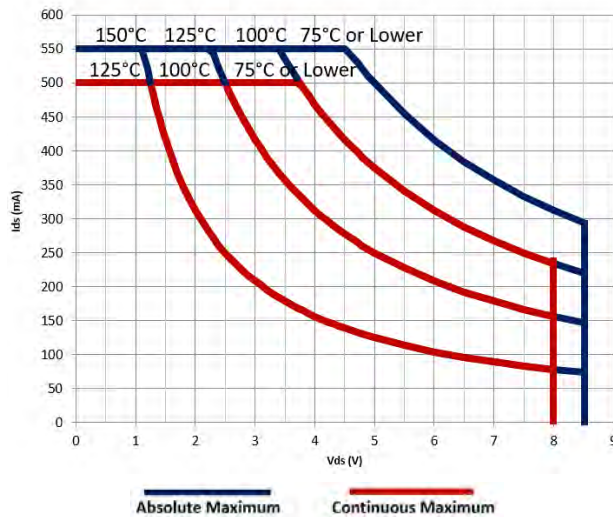
MwT-PH8F, Load Pull Power Data, Vds=8V; Idq=0.7xIdss

| Freq (GHz) | Zs   |       | ZL   |       | P <sub>sat</sub> (dBm) |
|------------|------|-------|------|-------|------------------------|
|            | mag  | phase | mag  | phase |                        |
| 2          | 0.70 | 130.0 | 0.32 | 175.3 | 31.0                   |
| 4          | 0.90 | 155.0 | 0.40 | 163.5 | 30.5                   |
| 6          | 0.95 | 170.0 | 0.36 | 168.0 | 30.9                   |
| 8          | 0.85 | 173.0 | 0.42 | 163.3 | 30.7                   |
| 10         | 0.90 | 180.0 | 0.51 | 159.7 | 30.6                   |
| 12         | 0.90 | 179.4 | 0.56 | 158.5 | 30.4                   |

The load pull data is based on nonlinear model provided by the foundry that processes the device.



SAFE OPERATING LIMITS vs BACKSIDE TEMPERATURE  
MwT-PH8F Chip and 71 Pkg



## Absolute Maximum Rating

| Symbol | Parameter             | Units | Cont Max1   | Absolute Max2 |
|--------|-----------------------|-------|-------------|---------------|
| VDS    | Drain to Source Volt. | V     | 8.0         | 8.5           |
| Tch    | Channel Temperature   | °C    | +150        | +175          |
| Tst    | Storage Temperature   | °C    | -65 to +150 | +175          |
| Pin    | RF Input Power        | mW    | 240         | 360           |

**Notes:**

1. Exceeding any one of these limits in continuous operation may reduce the mean-time-to-failure below the design goal.
2. Exceeding any one of these limits may cause permanent damage.